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PCB Number: SAT0077
PCB Rev. E1

PCB Label

1. These assemblies are ESD sensitive, ESD precautions shall be observed.
2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Mounting Holes

MH1 MH2 MH3 MH4

MH 3.2MM MH 3.2MM MH 3.2MM

Fiducials Marking

FID1 FID2 FID3 FID4 FID5 FID6

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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